



MESSAGE FROM THE 2010 MicroApps CHAIR

The Microwave Application Seminars (MicroApps), now in their 14th year, serve as a forum for exhibitors at the International Microwave Symposium to present the technology behind their commercial products and their special capabilities. The presentations are 20 minutes in length and are open to all conference and exhibit attendees. Everyone who attends MicroApps receives a free CD-ROM, which includes informative details from every presentation. We hope you expand your knowledge of advances in the current microwave industry by attending the presentations May 25 – 27 in the MicroApps Theater on the IMS2010 exhibition floor.

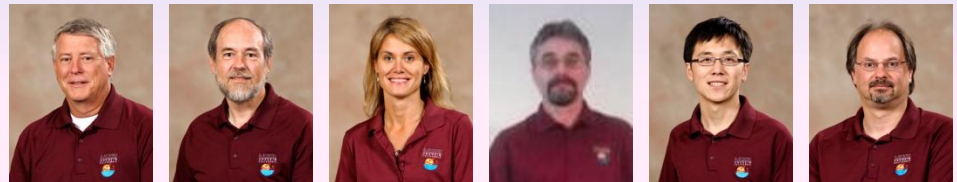
James Weiler,
IMS 2010 MicroApps Chair



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IMS 2010 MicroApps Committee



Phil Arnold Gary Hawisher Sherry Hess Mircea Metes Bo Pan Robert Welstand

MicroApps Schedule Tuesday May 25, 2010

9:10	<u>Design-Stage Thermal Analysis Using Templates</u> Shariar Motakef , Cape Sym, Inc.
9:30	<u>Multi-chip Module Design Challenges</u> Josh Moore, Dustin Hoekstra , AWR Corp.
9:50	<u>How to Prevent MMIC/RFIC Packaging Integration Failures</u> Hee-Soo Lee , Agilent Technologies
10:10	<u>Nonlinear Co-simulation with Real-time Channel Measurements for PCB Signal Integrity</u> Mike Heimlich , Macquire University, Khaled Nikro , AWR Corp., Harry Momjian , Anritsu Corp.
10:30	<u>Causality Considerations for Multi-Gigabit StatEye Analysis</u> Mike Heimlich , Macquire University, Scott Wedge, Ted Mido , Synopsys
10:50	<u>Do Something Really Useful with VNA Time Domain Processing</u> Don Metzger , Constant Wave
11:10	<u>Unexpected Effects of Conductor Profile on the Propagation Constant in Rogers RO4000® LoPro™ High Frequency Laminates</u> Allen F. Horn, II , Rogers Corp.
11:30	<u>Microvias for Microwave Applications in Co-fired Ceramics</u> Iris Labadie , Kyocera America, Inc.
11:50	<u>Drop-on-demand Inkjet Printing of Functional Materials Using the Dimatix Materials Printer DMP-3000</u> Jan Sumerel , FUJIFILM Dimatix, Inc.
12:10	<u>Characterization Of Adhesive Films From kHz to GHz</u> Deitmar Koether, Uwe Gollor, Joerg Berben , IMST GmbH
12:30	<u>Advances in High Frequency Printed Circuit Board (PCB) Materials Used in Power Amplifier Applications</u> John Coonrod , Rogers Corp.
12:50	<u>How to Save Money by Using Custom Designed GaAs MMICs</u> Liam Devlin , Plextek Limited

13:10	<u>System-Level Component Models for RF EDA</u> Jiang Liu, Lawrence Dunleavy , Modelithics, Inc.
13:30	<u>Multi-Rate Harmonic Balance for Non-Linear Simulation</u> Josh Moore , AWR Corp.
13:50	<u>A Survey of Load-Pull Simulation Capabilities – How Do They Help You Design Power Amplifiers?</u> Andy Howard , Agilent Technologies
14:10	<u>PA Design Inclusive of Load-Pull Analysis</u> Josh Moore, Dustin Hoekstra , AWR Corp.
14:30	<u>Online Design Environment Provide Interactive Datasheets for Small Signal RF Transistors – Allows Users to Generate Custom Datasheets for a Variety of Operating Conditions</u> Sherry Hess , AWR Corp., Uwe Knorr , Transim Technology Corp., Ronald Thisser , NXP Semiconductors
14:50	<u>Using AWR's iFilter™ wizard to efficiently synthesize lumped & distributed filters</u> Mark Saffian , AWR Corp.
15:10	<u>Synthesis, Design and High-power Analysis of Dual-mode Filters with FEST3D</u> Jordi Gil Raga, Carlos Vicente, Vincente Esbert Boria, Benito Gimeno , Aurora Software and Testing S.L.
15:30	<u>Creating and Tuning a Conformal Antenna with Remcom's XF 7 Software</u> James F. Stack, Jr. , Remcom, Inc.
15:50	<u>Ultraminiature High Power RF Switch</u> Werner Johler , Tyco Electronics
16:10	<u>Silicon Technology Solutions for Wireless Front End Modules</u> Alvin Joseph, Randy Wolf, Peter Rabbeni, Alan Botula, David Haramé, Jim Dunn , IBM Microelectronics
16:30	<u>Single Chip LNA using high Q inductors on a Silicon-on-Sapphire process</u> Duncan Widman , AWR Corp., Andrew Greatbatch , Sapphicon Semiconductor

■ Software/signal processing

■ Materials

■ Component modeling

MicroApps Schedule Wednesday May 26, 2010

9:10	<u>High-Power Measurements Using the Agilent Nonlinear Vector Network Analyzer</u> Keith Anderson , Agilent Technologies
9:30	<u>An Introduction to Gallium Nitride (GaN) Device Characterization</u> Steve Dudkiewicz , Maury Microwave Corp.
9:50	KEYNOTE: X-parameters™: The Emerging Paradigm for Interoperable Characterization, Modeling, and Design of Nonlinear Microwave and RF Components and Systems David Root , Agilent Technologies
10:50	<u>Redefine How You Measure & Simulate Nonlinear Devices Using X-Parameters™</u> Jack Sifri , Agilent Technologies
11:10	<u>S-functions, the “S-parameters” for Nonlinear Devices</u> Guillaume PAILLONCY , NMDG nv
11:30	<u>A New Approach for Nonlinear Behavioral Modeling</u> Darren McCarthy , Tektronix Inc., Johannes Benedik , Mesuro Limitex
11:50	<u>Accurate Mixer Measurements Using Multi-tone X-parameter™ Models</u> Mihai Marcu, Radek Biernacki , Agilent Technologies
12:10	Lunch
12:30	<u>A Methodical Approach to Analyzing and Understanding the Performance of a LTE System</u> Joel Kirshman , AWR Corp.
12:50	<u>Practical Digital Pre-Distortion Techniques for Linearization in 3GPP LTE Systems</u> Jin-Biao Xu , Agilent Technologies
13:10	<u>Wideband Linearization</u> Allen Katz , Linearizer Technology, Inc.

13:30	<u>EMPIRE XCcel – Efficient solving of large scale EM problems</u> Winfried Simon, A. Wien , IMST GmbH
13:50	<u>XFDTD 7 and Wireless InSite: Remcom's Multi-Physics Toolset</u> Joseph J. Rokita , Remcom, Inc.
14:10	<u>When Should You Apply Planar EM Simulation?</u> Andy Howard , Agilent Technologies
14:30	<u>Rapid 3-D Analysis of Multiple Design Configurations with HFWorks</u> Hussam Maleh, Kousseil Ben Ahmed , ElectroMagnetic Works
14:50	<u>The Use of Computer Clusters and Spectral and Domain Decomposition in 3D FEM Analysis</u> John DeFord , AWR Corp.
15:10	<u>Low Phase Noise Signal Generation and Measurement</u> John S. Hansen , Agilent Technologies
15:30	<u>Miniature Low Phase Noise Microwave Opto-electronic Oscillator (OEO)</u> Danny Fung , OEwaves, Inc.
15:50	<u>Pulse Generation and Analysis</u> John S. Hansen , Agilent Technologies
16:10	<u>Modern Methods for Fast And Accurate Frequency Converter Characterization</u> David Ballo , Agilent Technologies
16:30	<u>Down-Converting Ultra Wideband Track and Hold Circuits</u> Mehran Mokhtari , Teledyne Scientific
16:50	<u>High Power Load Pull with X-Parameters – A New Paradigm for Modeling and Design</u> Gary Simpson , Maury Microwave Corp.
17:20	<u>A Tutorial on Silicon Spiral Inductor Ground Return Effects on RFIC Design</u> James Rautio , Sonnet Software, Inc.

MicroApps Schedule Thursday May 27, 2010

9:10	<u>Practical Considerations in the Design and Implementation of RF and Microwave Signal Switching Solutions for ATE</u> Walt Strickler , Giga-tronics Incorporated
9:30	<u>Test & Measurement Migration to Integrated Simulation, Test & Measurement for M&RF Design</u> Christina Gessner , Rohde & Schwarz, Sherry Hess , AWR Corp.
9:50	<u>Fundamentals of Phase-Coherent RF Measurements</u> David A. Hall , National Instruments
10:10	<u>Mobile Phone Testing Using Impedance Tuner</u> Roman Meierer , Steve Dudkiewicz , Maury Microwave Corp.
10:30	<u>Improved Amplifier Testing Using Statistics</u> Bob Muro , Wireless Telecom Group
10:50	<u>Detailed Comparison of Dynamic Range Between a Vector Network Analyzer and Sampling Oscilloscope Based Time Domain Reflectometer by Normalizing Measurement Time</u> Sho Okuyama , Agilent Technologies International Japan, Ltd.

11:10	<u>Ultra-Fast Noise Parameter Measurements – 100x Faster and More Accurate</u> Gary Simpson , Maury Microwave Corp.
11:30	<u>WinCal the Microwave Tool</u> Leonard Hayden , Cascade Microtech, Inc.
11:50	<u>Coaxial Measurements – Common Mistakes and Simple Solutions</u> Sathya Padmanabhan , Rocky Teresa , Maury Microwave Corp.
12:10	<u>Application of second-tier VNA calibration with Cascade Microtech WinCal XE</u> Craig Kirkpatrick , Cascade Microtech, Inc.
12:30	<u>The Challenges of the Nanoscale Material and Device Characterization</u> Hassan Tanbakuchi , Pavel Kabos , Agilent Technologies
12:50	<u>60 GHz Power Amplifier Design for Wireless HDMI (WPAN)</u> Michael Thompson , Agilent Technologies, Ken Mays , TriQuint Semiconductor

■ Test and measurement

■ Software/signal processing